

PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
Application Number:	14521609
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DATE SIGNED:	10/23/2014
Total Attachments: 2	
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source=2018-3462_Assignment#page2.tif	

譲渡証 ASSIGNMENT

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譲受者名:
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DENSO CORPORATION

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as Assignee(s), and corresponding successors, assigns or other legal representatives, the entire right, title and interest, in the United States of America, and its territories, dependencies and possessions, to certain inventions known as

発明の名称:
Title of
Invention:

**SEMICONDUCTOR PACKAGE AND WIRING BOARD HAVING THE
SEMICONDUCTOR PACKAGE THEREON**

上記発明についての米国登録特許証の出願は、
described in an application for Letters Patent of the United States executed



本譲渡証と同日、もしくは
on even date herewith



米国出願番号 _____ として _____ に提出されたものです。
as U.S. Application Serial No. _ filed on _

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The undersigned agree(s), when requested, to sign all papers, take all rightful oaths, and perform all acts which may be necessary for securing, maintaining and enforcing patents for said inventions and for vesting title thereto in said Assignee(s).

The undersigned authorize(s) and empower(s) said Assignee(s) to invoke and claim the benefit of the right of priority provided under any and all international conventions and treaties in respect of said inventions, as may be necessary in connection with said application.

The undersigned also authorize(s) Nixon & Vanderhye P.C. to insert hereon any further identification that may be necessary or desirable for recordation of this document.

発明者はここに付随する添付書面上にリストされます。

inventor(s) listed on the attached sheet which is incorporated herein by reference.

注記: 上記日本語抄訳は、本書面の理解の助けとして付記しております。正式な解釈は英文に基づき行われます。

Note: The above Japanese text is for the purpose of helping the understanding of the reader. The interpretation of the Assignment should be based on the English text.

譲渡証(続き)
ASSIGNMENT (Cont.)

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